RDC4 Meeting Dec 12, 2024

CPAD 2024 -- RDC4 Electronics & ASICs

https://indico.phy.ornl.gov/event/510/page/138-conference-program

~260 in person (and a few remote) participants

o 64 students

8 plenary sessions29 parallel sessions (with 163 presentations)21 posters

Special topic:

50 years of TPC's Wednesday Morning in 4 Plenary talks finishing up with David Nygren's recollections

Ian Shipsey Memorial by Marcel Demarteau



see also Closeout presentation for a brief synopsis by RDC topical area: CPAD Closeout

CPAD summary RDC4: Readout and ASICs

- Workshop statistics: 4 parallel sessions, 24 presentations
- Highlights
 - 4D tracking: collaboration is forming, highlights from 1st workshop
 - TPC pixel readouts:
 - LaArPix and beyond…

 Qpix (ultimate power?), GamPix (20 el. w/trigger?), TopMetal (3 el. !!?)
 - Potential meetings between QPix and LaArPix community
- Cross RDC interactions:
 - RDC1: Readout ASICs for TPCs
 - RDC3: Sensors for 4D tracking
 - RDC3: MAPS
 - RDC3: Interconnections
 - RDC8: ASICs for SNSPD/SQUID biasing & readout
 - RDC9: we need closer collaboration

CPAD summary RDC4: Readout and ASICs

Lorenzo Rota Mitch Newcomer

- Potential work packages
 - 4D tracking: analog front-end, TDC, CFD, 3D integration
 - Cryogenic:
 - mK-4K: ICs for SQUID biasing & amplification, IPs (PLL, TDC)
 - 77-165K: Analog front-end on 65nm, QPix news, LaArPix
 - AI/ML: Smart pixels, eFPGA, anomaly detection, unconventional computing
 - Photon readout: readout SiPM arrays, feature extraction from PMTs
 - Photonic data links: cryogenic & radiation-hard with ring modulators
- Discussions and Next Steps
 - Joint RDC04 & RDC09 (Electronics & Calorimetry) meetings to understand unique needs and potential service requirements for calorimetry.
 - MAPS vs wafer-wafer bonded hybrid: where do we draw the line?
 - Do we need/want an interconnect work-package? Joint discussion with RDC3
 - Al/ML: where is the best place to implement it, and can we live with the area/power budget?
 - o Potential services to other topical communities: e.g., SEU protection, verification, etc...

Future topics for RDC4 meeting discussions

RDC4 – Service packages .. An interesting/useful topic being discussed in DRD7

- Sensor Module Simulation CoDesign tools / Verification etc...
- Detector level generic support available to all topical areas encourage a detector aware design approach.
- Monitoring / Slow control ...

Joint Meetings

- RDC 9 Calorimetry
- RDC 2 Photonics
- RDC 3 Readout Electronics for Solid State Trackers
- RDC 5 Triggering

etc...

Discussion Today of a possible Interconnect work Package

Novel Interconnect Techniques for Hybrid multi-D tracking Pixel detectors

- Mutual RDC3 (Solid State Tracking) RDC4 (Electronics) interest driven by the independence of Sensor of Readout Technology.
- What is the current "State of the Art" in interconnect
- What directed R&D is currently underway
- What Specifications would be compelling enough to garner Community interest.